

N&P-Channel MOSFET

General Description

The WSP4067 is the highest performance trench N-ch and P-ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSP4067 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

Absolute Maximum Ratings

Product Summery

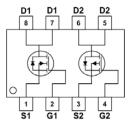
BVDSS	RDSON	ID
40V	21mΩ	7.5A
-40V	38mΩ	-5.5A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter.
- Networking DC-DC Power System
- Load Switch

SOP-8 Pin Configuration





		Rat	ting	
Symbol	Parameter	N-Channel	P-Channel	Units
V _{DS}	Drain-Source Voltage	40	-40	V
V _{GS}	Gate-Source Voltage	±20	±20	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	7.5	-5.5	A
I _D @T _C =70℃	Continuous Drain Current, V _{GS} @ 10V ¹	6	-4.5	А
I _{DM}	Pulsed Drain Current ²	30	-20	А
EAS	Single Pulse Avalanche Energy ³	25	25	mJ
I _{AS}	Avalanche Current	10	10	А
P _D @T _C =25℃	Total Power Dissipation ⁴	2	2	W
T _{STG}	Storage Temperature Range	-55 to 150	-55 to 150	°C
TJ	Operating Junction Temperature Range	150	150	°C

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
R _{0JA}	Thermal Resistance Junction-Ambient ¹		62.5	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹		50	°C/W



Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	40			V
$\triangle BV_{DSS} / \triangle T_J$	BV _{DSS} Temperature Coefficient	Reference to $25^\circ C$, I _D =1mA		0.067		V/℃
D	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =6A		16	21	
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =4.5V , I _D =5A		18	25	mΩ
V _{GS(th)}	Gate Threshold Voltage		1.5	2	2.5	V
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	— V _{GS} =V _{DS} , I _D =250uA		-5.24		mV/℃
	Drain Source Lookage Current	V _{DS} =32V , V _{GS} =0V , T _J =85℃			1	uA
I _{DSS}	Drain-Source Leakage Current	V _{DS} =32V , V _{GS} =0V , T _J =85℃			30	
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm20V$, $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =8A		24		S
R _g	Gate Resistance	V_{DS} =0V , V_{GS} =0V , f=1MHz		2.5		Ω
Qg	Total Gate Charge (4.5V)			15.7	22	
Q _{gs}	Gate-Source Charge	V _{DS} =20V , V _{GS} =10V , I _D =6A		3.24		nC
Q _{gd}	Gate-Drain Charge			2.75		
T _{d(on)}	Turn-On Delay Time			7.8		
Tr	Rise Time	V _{DD} =20V , V _{GS} =10V ,		6.9		
T _{d(off)}	Turn-Off Delay Time	R _G =6Ω, I _D =1Α ,R∟=20Ω		22.4		ns
T _f	Fall Time			4.8		
C _{iss}	Input Capacitance			815		
Coss	Output Capacitance			95		pF
C _{rss}	Reverse Transfer Capacitance			60		

N-Channel Electrical Characteristics (TJ=25 °C, unless otherwise noted)

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	V _{DD} =25V , L=0.1mH , I _{AS} =16A	11.2			mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,6}	$V_G = V_D = 0V$, Force Current			6.0	А
I _{SM}	Pulsed Source Current ^{2,6}				24	А
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1.7A,T _J =25℃			1.1	V

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec.

2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%

3. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V, L=0.1mH, I_{AS} =16A

4. The power dissipation is limited by 150 °C junction temperature

5. The Min. value is 100% EAS tested guarantee.

6.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-40			V
$\triangle BV_{DSS} / \triangle T_J$	BV _{DSS} Temperature Coefficient	Reference to 25 $^\circ\!\mathrm{C}$, I_D=-1mA		-0.03		V/℃
Deserve	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-5.5A		30	38	
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =-4.5V , I _D =-3.5A		46	62	mΩ
V _{GS(th)}	Gate Threshold Voltage		-1.5	-2.0	-2.5	V
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	—V _{GS} =V _{DS} , I _D =-250uA		4.56		mV/℃
	Drain Source Lookage Current	V _{DS} =-32V , V _{GS} =0V , T _J =85℃			-1	uA
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-32V , V _{GS} =0V , T _J =85℃			-30	
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm20V$, V_{DS} = $0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-4.5A		18		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		8		Ω
Qg	Total Gate Charge (-4.5V)			7.5		
Q _{gs}	Gate-Source Charge	V _{DS} =-20V , V _{GS} =-10V , I _D =-5.5A		2.4		nC
Q _{gd}	Gate-Drain Charge			3.5		
T _{d(on)}	Turn-On Delay Time			8.7		
Tr	Rise Time	V _{DD} =-20V , V _{GS} =-10V ,		7		
T _{d(off)}	Turn-Off Delay Time	R _G =6Ω, I _D =-1Α,R∟=20Ω.		31		ns
T _f	Fall Time			17		
C _{iss}	Input Capacitance			668		
Coss	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		98		pF
C _{rss}	Reverse Transfer Capacitance			72		

P-Channel Electrical Characteristics (T_J=25 $\,\,{}^\circ\!\!\!\!\!^\circ$, unless otherwise noted)

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	V _{DD} =-25V , L=0.1mH , I _{AS} =-18A	11			mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
ls	Continuous Source Current ^{1,6}	$V_{G}=V_{D}=0V$, Force Current			-5.5	А
I _{SM}	Pulsed Source Current ^{2,6}				-20	А
V _{SD}	Diode Forward Voltage ²	V_{GS} =0V , I_{S} =-1A , T_{J} =25 $^{\circ}\mathrm{C}$			-1.1	V

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10 sec.

2.The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%

3. The EAS data shows Max. rating . The test condition is V_{DD} =-25V, V_{GS} =-10V, L=0.1mH, I_{AS} =-18A

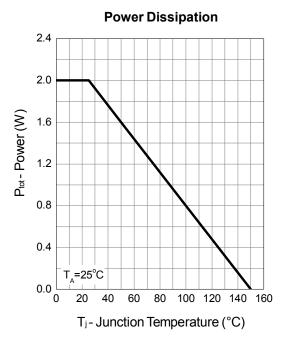
4.The power dissipation is limited by 150 $^\circ\!\!\!\mathrm{C}$ junction temperature

5. The Min. value is 100% EAS tested guarantee.

6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



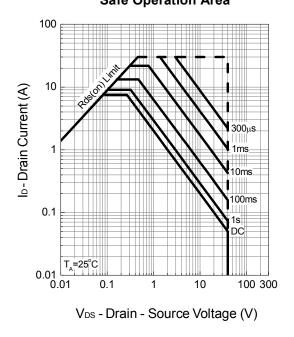
N-Channel Typical Characteristics



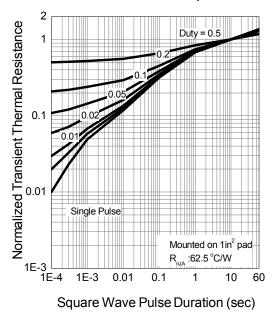
9.0 7.5 Ip-Drain Current (A) 6.0 4.5 3.0 1.5 =10V Т 0.0 80 100 120 140 160 0 20 40 60 T_j-Junction Temperature (°C)

Drain Current

Safe Operation Area

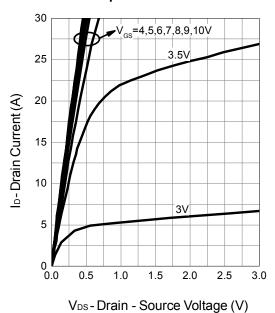


Thermal Transient Impedance

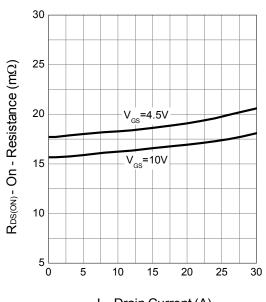




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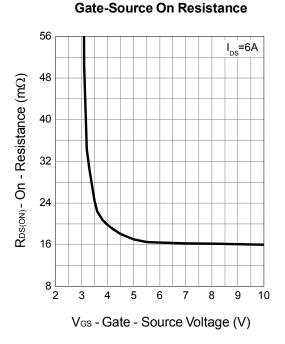


Output Characteristics

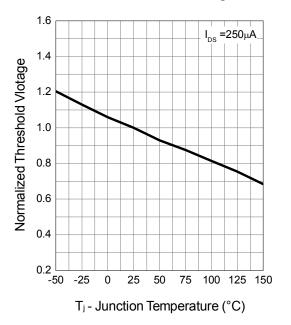


Drain-Source On Resistance

ID-Drain Current (A)

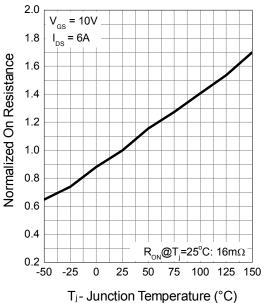


Gate Threshold Voltage

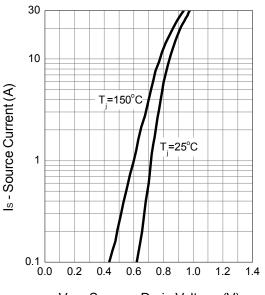




N&P-Channel MOSFET

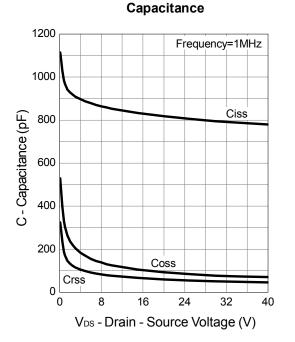


Drain-Source On Resistance

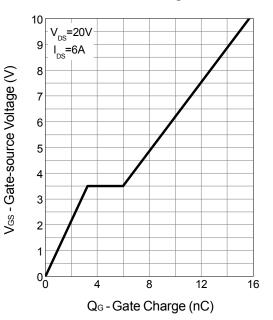


Source-Drain Diode Forward

 $V_{\mbox{\scriptsize SD}}$ - Source - Drain Voltage (V)

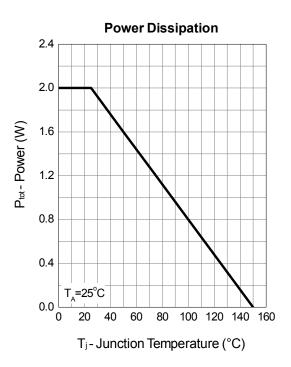


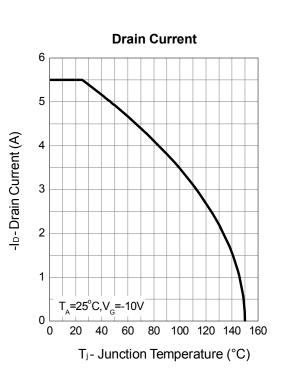
Gate Charge





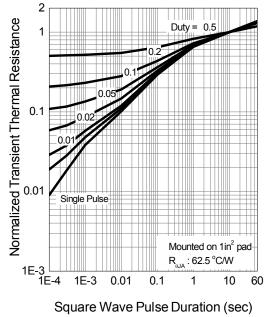
P-Channel Typical Characteristics





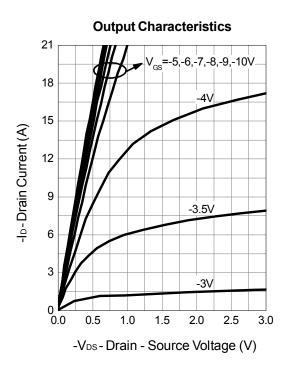
Safe Operation Area 100 10 -lp- Drain Current (A) 00µs 1ms 1 10ms 100ms 0.1 1s DC 0.01 <u>^</u> 0.01 0.1 10 100 300 1 -VDS - Drain - Source Voltage (V)

Thermal Transient Impedance





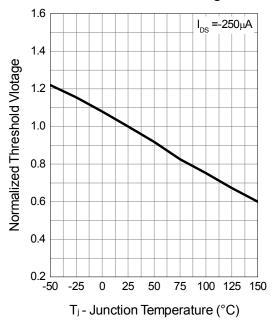
N&P-Channel MOSFET



Drain-Source On Resistance 80 70 $R_{DS(ON)}$ - On - Resistance (m Ω) 60 V_{GS}=-4.5V 50 40 V_{GS}=-10V 30 20 10 └─ 0 4 8 12 16 20 -ID- Drain Current (A)

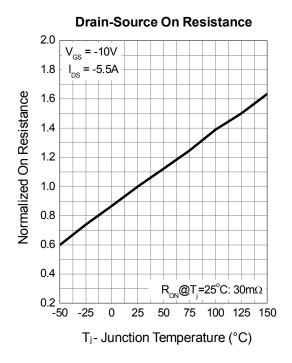
Gate-Source On Resistance 140 I_{DS}=-5.5A 120 $R_{DS(ON)}$ - On - Resistance (m Ω) 100 80 60 40 20 0 L 2 5 6 7 8 3 4 9 10 -VGS - Gate - Source Voltage (V)

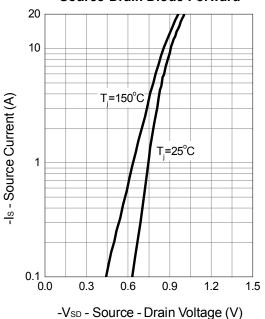
Gate Threshold Voltage



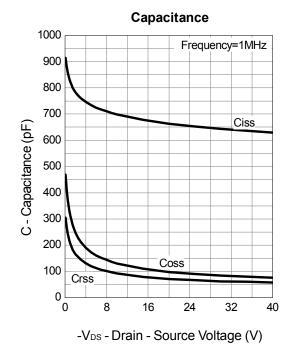


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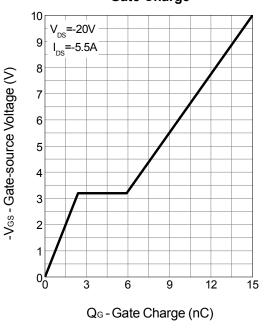




Source-Drain Diode Forward



Gate Charge





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